

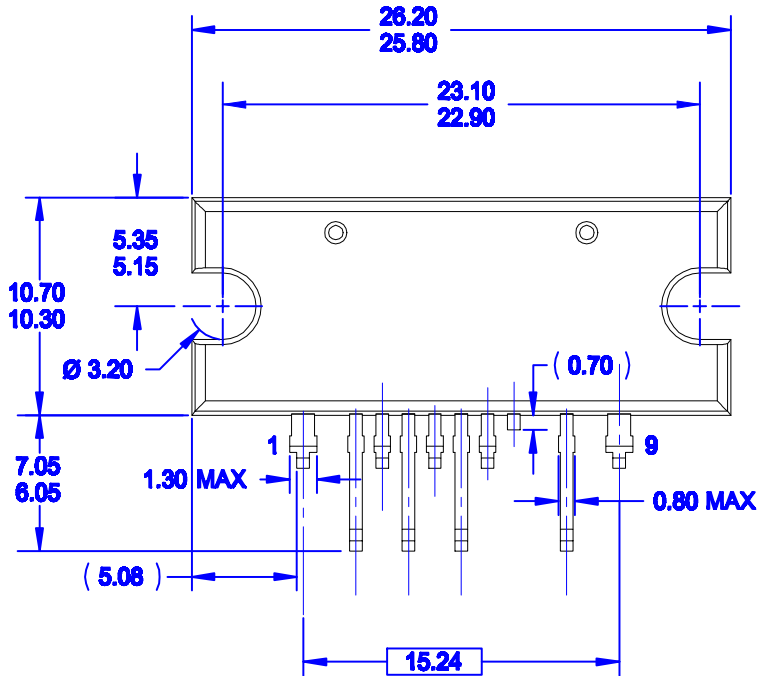
MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

ON Semiconductor®

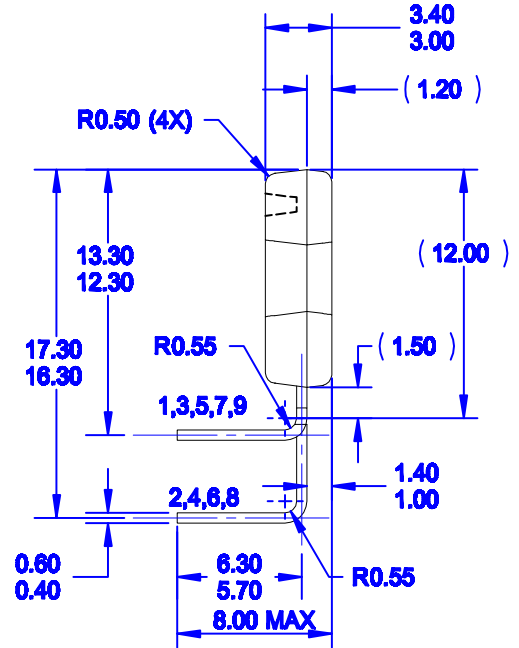


SIP9 26x10.5
CASE 127EN
ISSUE O

DATE 31 DEC 2016

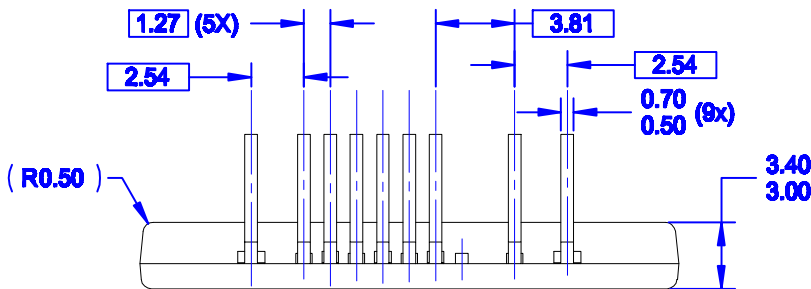


BOTTOM VIEW



RIGHT SIDE VIEW

Note: Terminal face upwards



BACK VIEW

NOTES: UNLESS OTHERWISE SPECIFIED

- A. THIS PACKAGE DOES NOT COMPLY TO ANY CURRENT PACKAGING STANDARD.**
- B. ALL DIMENSIONS ARE IN MILLIMETERS.**
- C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH AND TIE BAR PROTRUSIONS.**

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